US006428650B1

(12) **United States Patent**
Chung

(10) **Patent No.: US 6,428,650 B1**
(45) **Date of Patent: Aug. 6, 2002**

(54) **COVER FOR AN OPTICAL DEVICE AND METHOD FOR MAKING SAME**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 2 days.

(21) Appl. No.: **09/633,791**

(22) Filed: **Aug. 7, 2000**

Related U.S. Application Data

(63) Continuation-in-part of application No. 09/232,936, filed on Jan. 9, 1999, now Pat. No. 6,136,122.
(60) Provisional application No. 60/090,295, filed on Jun. 23, 1998, provisional application No. 60/092,170, filed on Jul. 9, 1998, and provisional application No. 60/198,705, filed on Apr. 20, 2000.

(51) **Int. Cl.**[7] **B32B 31/18**; C09J 11/00; H01L 21/463; H01L 31/0232; H05K 5/06

(52) **U.S. Cl.** **156/250**; 156/257; 156/277; 156/295; 156/69; 438/113; 438/116; 438/118; 438/144; 174/50.51; 174/52.3; 257/434; 250/239

(58) **Field of Search** ..... 156/235, 240, 156/241, 248, 250, 257, 265, 268, 277, 280, 291, 295, 69; 432/113, 114, 116, 118, 128; 174/50.51, 52.3; 257/81, 87, 433, 434, 264; 250/208.1, 214 R, 239

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(57) **ABSTRACT**

An optical device is enclosed within a package or module having an optically transmissive or transparent cover that is sealed with an adhesive preform that has been pre-applied onto the bonding areas of the cover. The adhesive preforms are formed of a wet adhesive deposited on a sheet of optically transmissive or transparent material as a preform in predetermined locations and are B-staged or dried to form dry solid adhesive preforms. The preforms may be continuous or have one or more small gaps therein. The sheet of optical material is diced or singulated to produce individual optical covers having an adhesive preform thereon.

34 Claims, 5 Drawing Sheets